

IPC-4555

2022 - April

**Performance Specification
for High Temperature
Organic Solderability Preservatives (OSP)
for Printed Boards**

An international standard developed by IPC



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Performance Specification for High Temperature Organic Solderability Preservatives (OSP) for Printed Boards

Developed by 4-14E Final Finishes for Printed Boards – OSP Task Group
of IPC

Users of this publication are encouraged to participate in the
development of future revisions.

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Final Finishes for Printed Boards - OSP Task Group (4-14E) of the Plating Processes Subcommittee (4-14) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of IPC extend their gratitude.

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